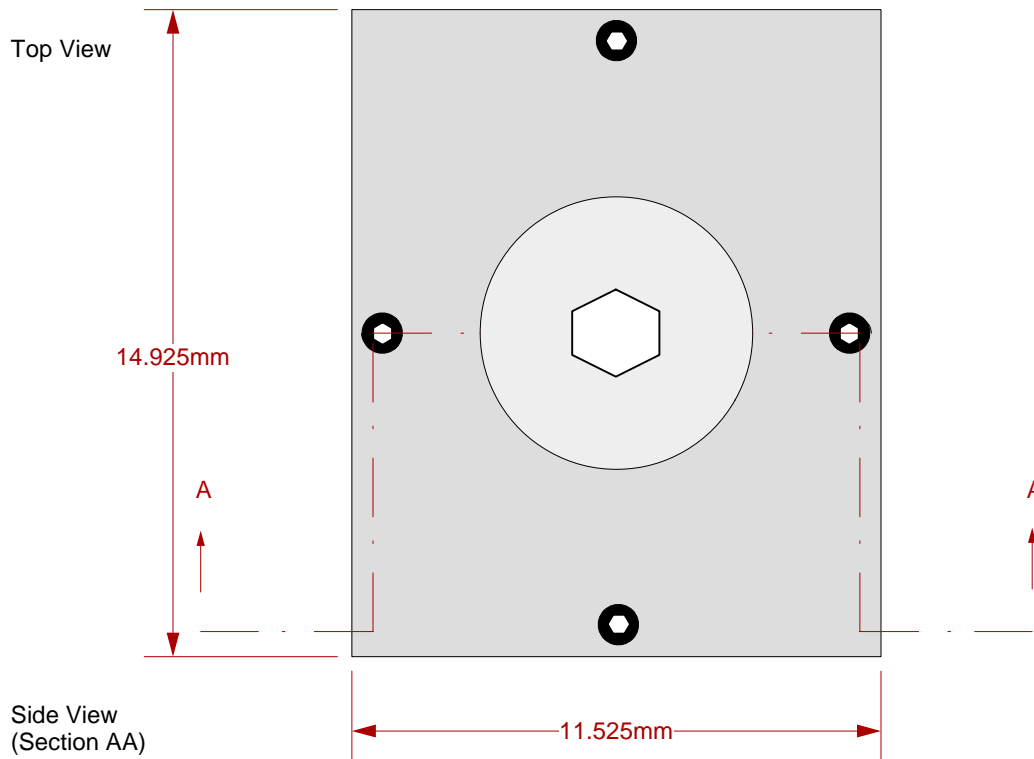


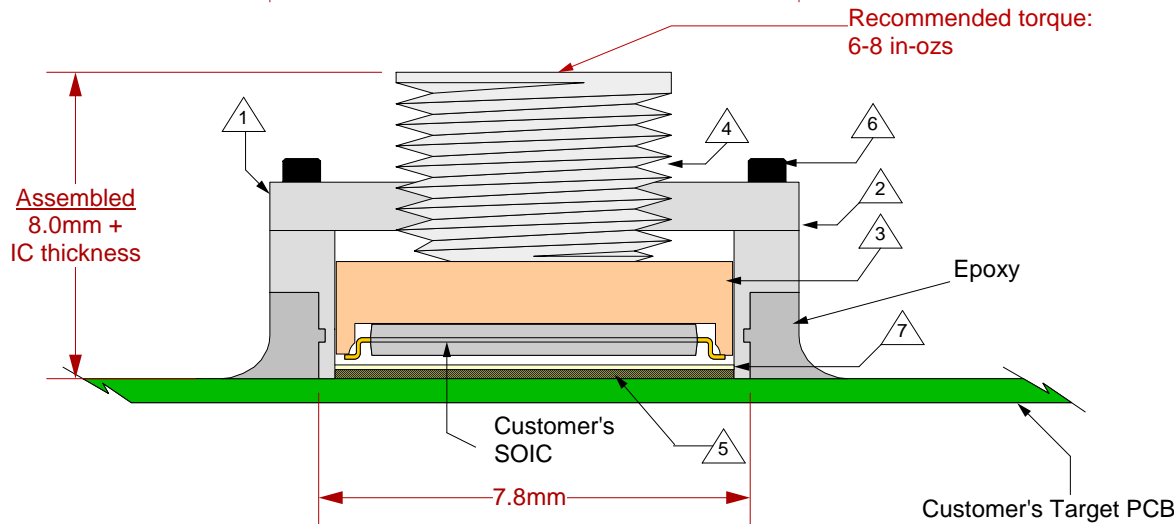
GHz MLF Socket - Epoxy mount, solderless



Features


- Directly mounts to target PCB (needs epoxy) .
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly

Side View
(Section AA)



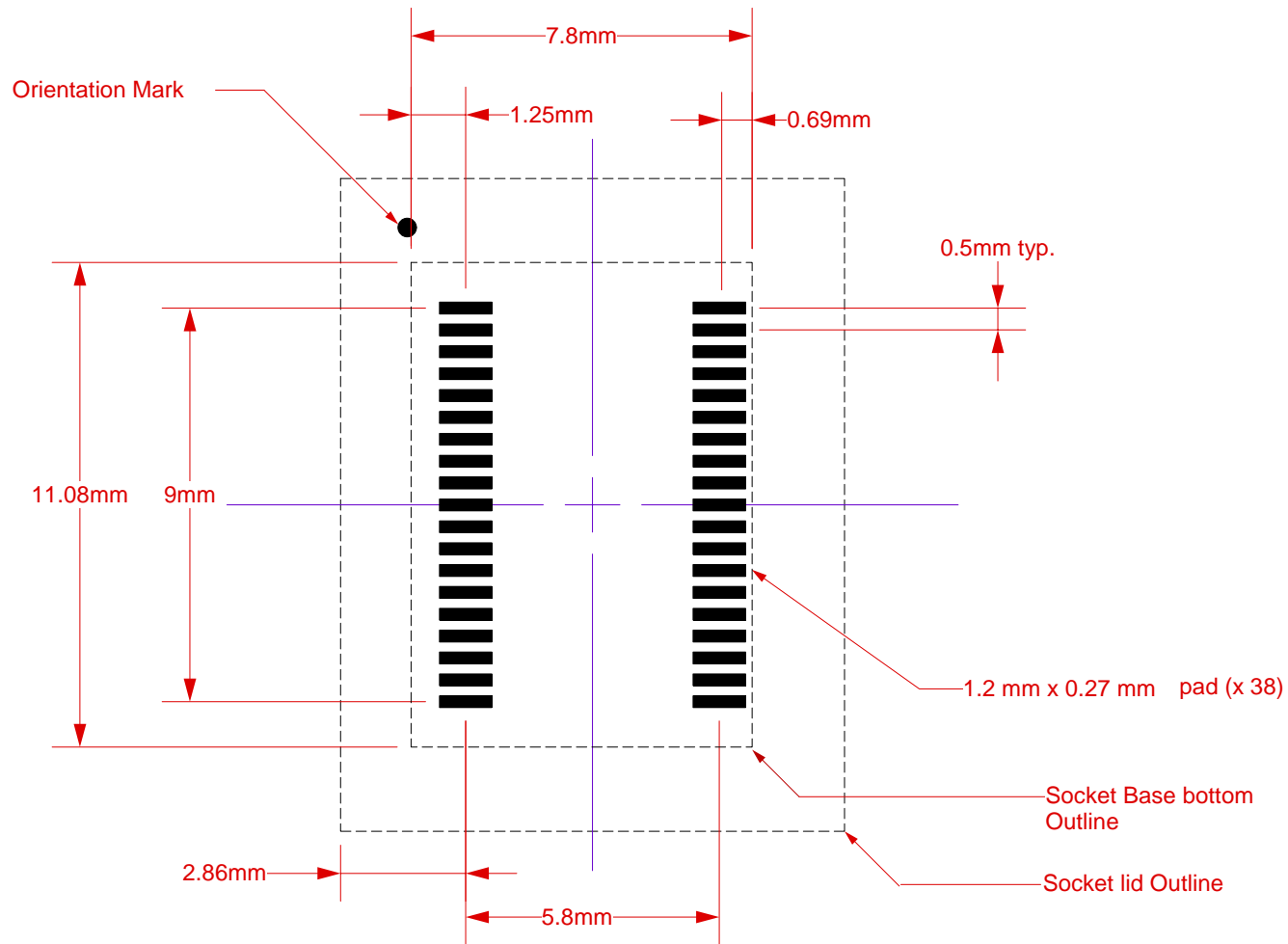
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Ultem. Thickness = 3.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 2mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Socket lid screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread , 4.76mm long.
- △ 7 Lead guide: Kapton.

Note: Alignment guide for positioning socket base to target PCB will be supplied.

SG-SOIC-3000 Drawing		Status: Released	Scale: -	Rev: A
 <p>© 2008 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 01/25/08	
	File: SG-SOIC-3000 Dwg		Modified:	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.


Recommended PCB Layout
Top View



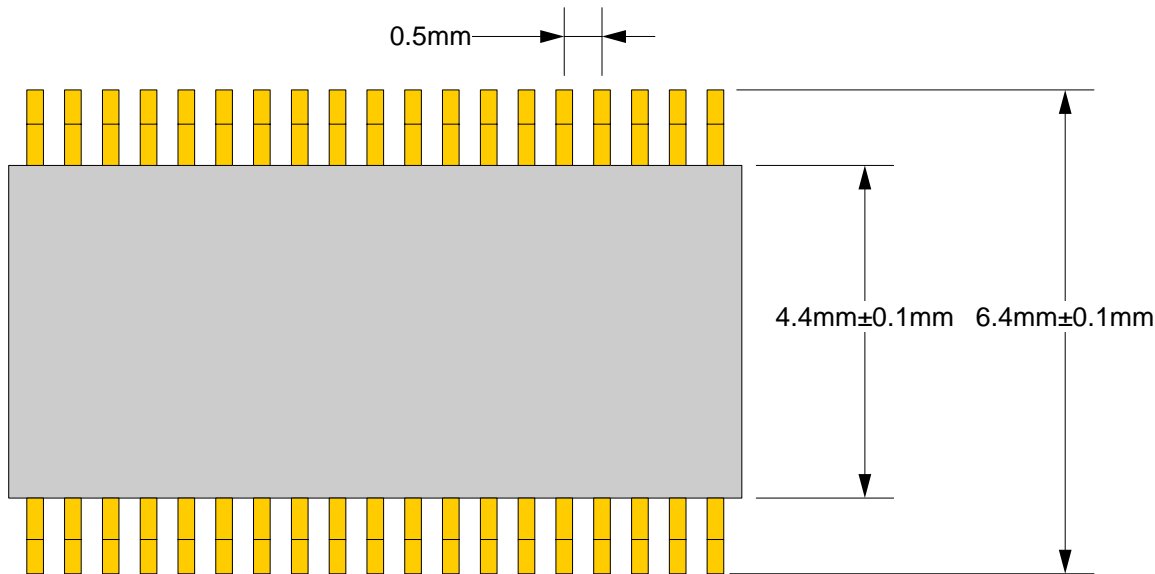
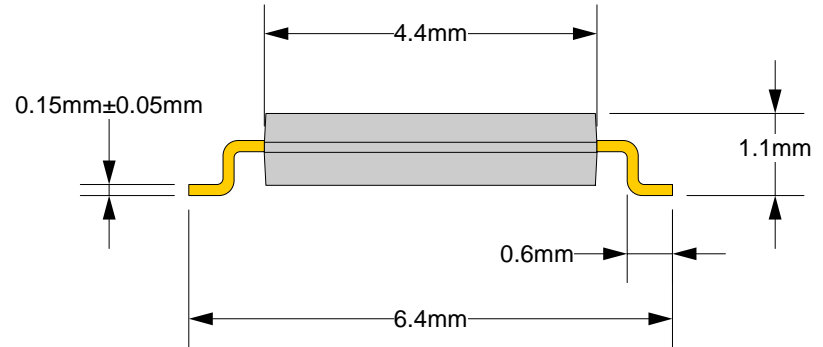
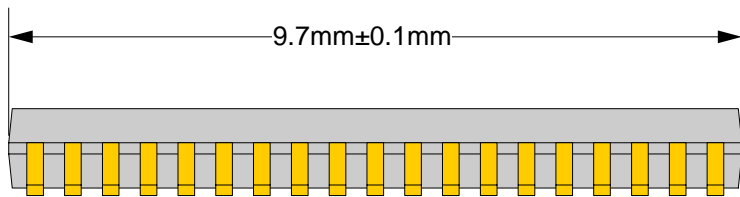
Target PCB Recommendations

Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask


Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

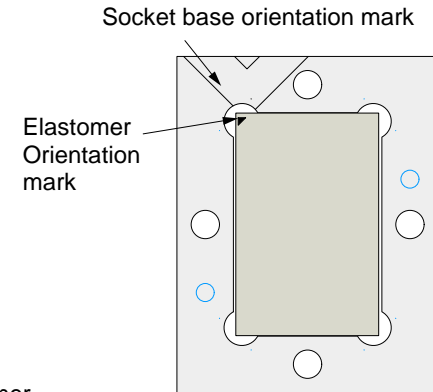
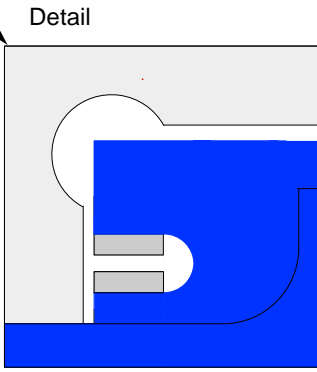
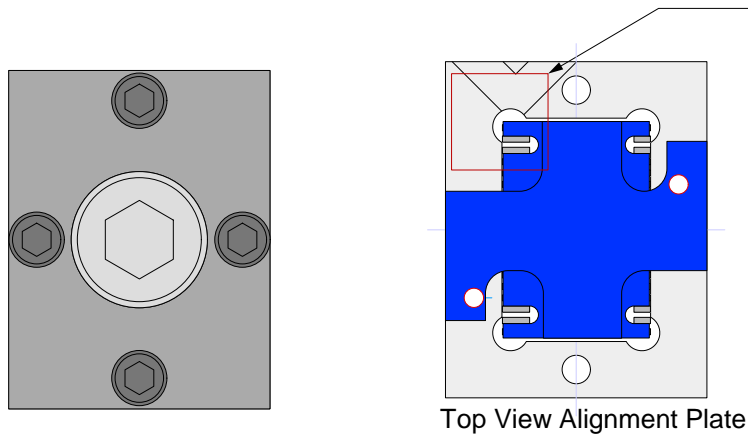
	SG-SOIC-3000 Drawing	Status: Released	Scale: 6:1	Rev: A
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		File: SG-SOIC-3000 Dwg	Modified:	

SOIC Package Specification:

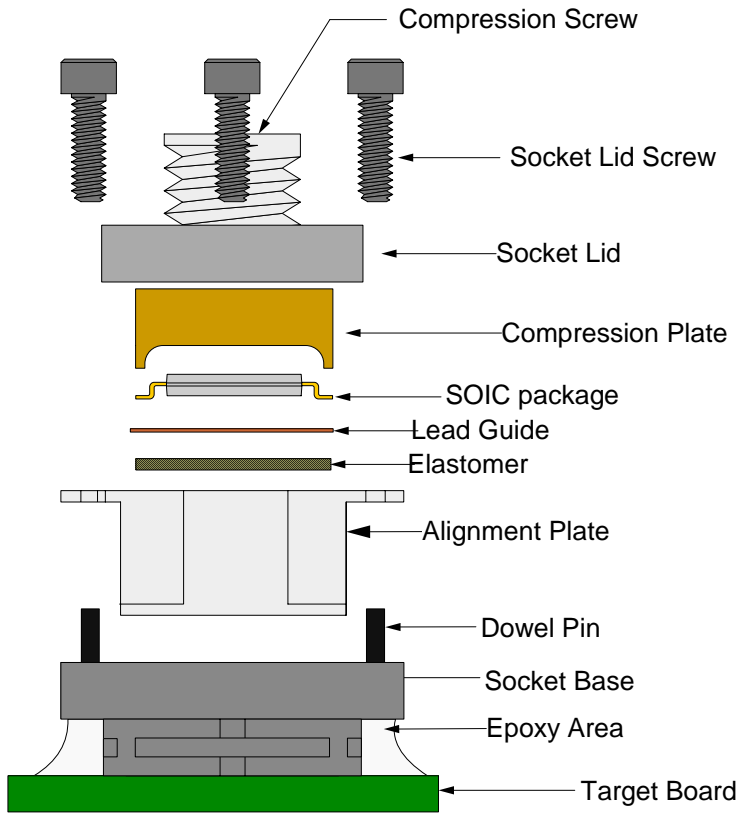
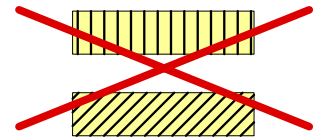


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Parallelism measurement shall exclude any effect of mark on top surface of package.

	SG-SOIC-3000 Drawing	Status: Released	Scale: 10:1	Rev: A
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		File: SG-SOIC-3000 Dwg	Modified:	




When elastomer orientation mark is on upper left corner, side view of elastomer should be



User Instructions:

1. Insert alignment plate onto dowel pins in socket base. Place alignment plate + socket base assembly onto target board.
2. Align tabs on alignment plate with corner pads on target board as shown above, hold socket base on to board tightly with finger and put a drop of super glue on each corner. Let it dry, remove the alignment plate, then run a bead of epoxy around socket base and let it cure until the epoxy is hardened. Recommended epoxy: DP110 (3M brand, 9 min work life). Other equivalent epoxies can be substituted. **Note: Do not cure in the oven.**
3. Place elastomer inside the socket base cavity (direction and orientation are critical) as shown above.
4. Place SOIC package and compression plate into the socket base cavity.
5. Assemble socket lid onto socket base with socket lid screws.
6. Assemble compression screw into socket lid and apply 6-8 in-oz torque.

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	<p>Drawing: J. Glab</p>	<p>Date: 01/25/08</p>		<p>Modified:</p>
	<p>File: SG-SOIC-3000 Dwg</p>			